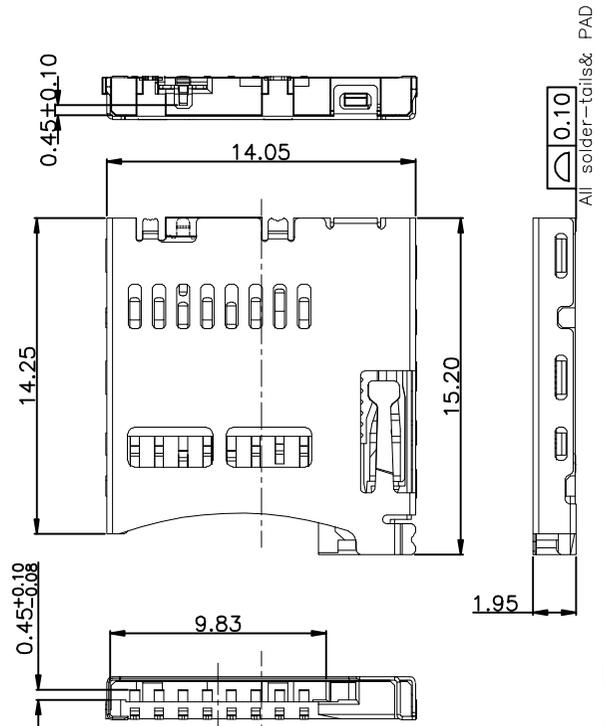
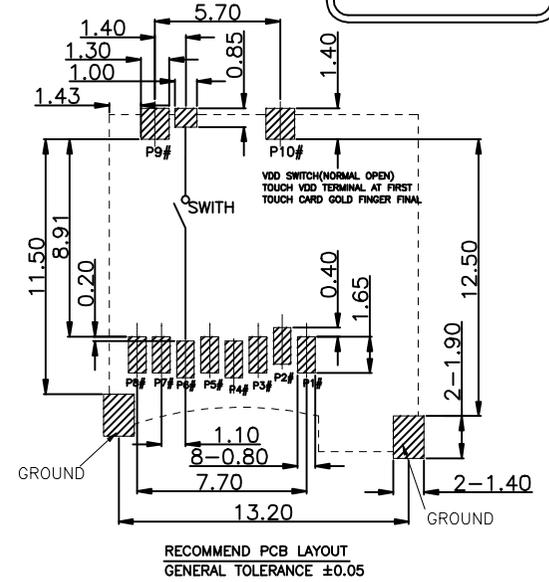
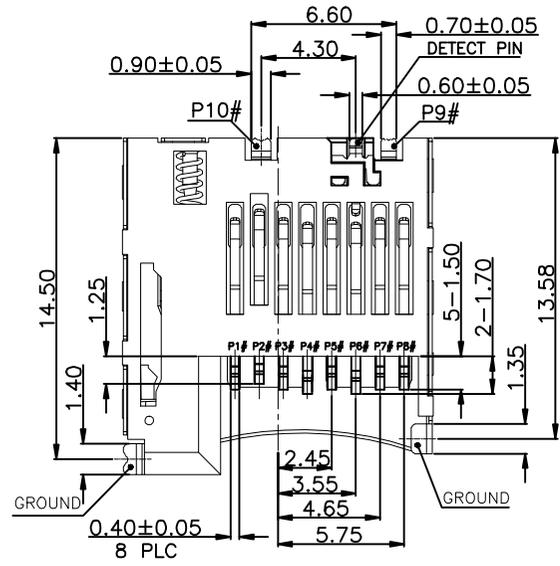


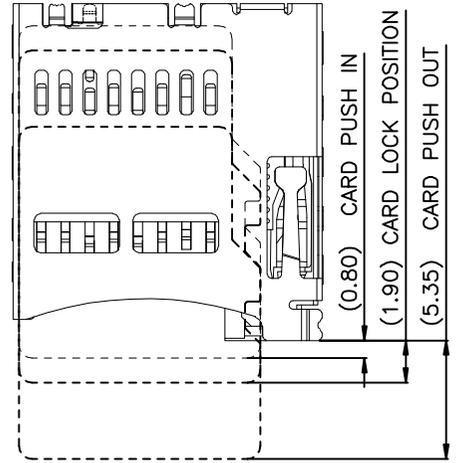
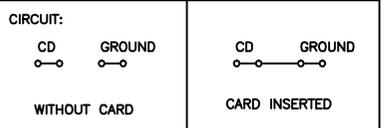
**RoHS**



All solder-tails & PAD  
0.10



Pin No.	MICRO SD
PIN1	DAT2 1P
PIN2	CD/DAT3 2P
PIN3	CMD 3P
PIN4	VDD 4P
PIN5	CLK 5P
PIN6	VSS 6P
PIN7	DAT0 7P
PIN8	DAT1 8P
PIN9	CARD DETECT
PIN10	



NOTES:  
 1) MATERIAL:  
 HOUSING : HI-TEMP. PLASIC UL 94V-0  
 CONTACT : COPPER ALLOY, T=0.15mm  
 SHELL : STAINLESS STEEL, T=0.15mm  
 2) FINISH :  
 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;  
 GOLD FLASH PLATED ON SOLDER TAILS,  
 SHELL: GOLD FLASH PLATED ON SOLDER TAILS,  
 3) PART NO.:

**LXW** 连兴旺电子(深圳)有限公司  
 LXWCONN ELECTRONICS (SHENZHEN) CO., LTD

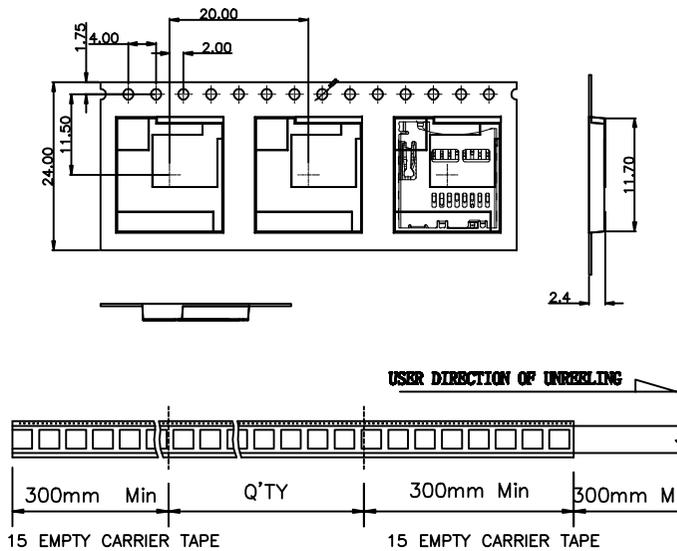
C	PRODUCT SPEC. T*
TITLE:	1.95H MICRO SD PUSH CONN的薄 翻开型
PART NO.	CS-376-08195W
FILE NAME:	
SCALE	1:1 UNIT:mm A4 SHEET: 1 of 1

General	Angle	设计	DESIGN	Nicolas	12'/08/20
X±0.50		校阅	CHECK	Nicolas	12'/08/20
.X±0.30	.X'±3'	承认	APPRO.		
.XX±0.20	.XX'±2'				
GENERAL TOLERANCE UNLESS OTHERWISE NOTED					

工程变更通知单号 ECN(DCN) NO.	版次 REV	日期 DATE	说明 DESCRIPTION	改变 CHANGE	承认 APPRO.
	A	12'/08/20	NEW RELEASE		



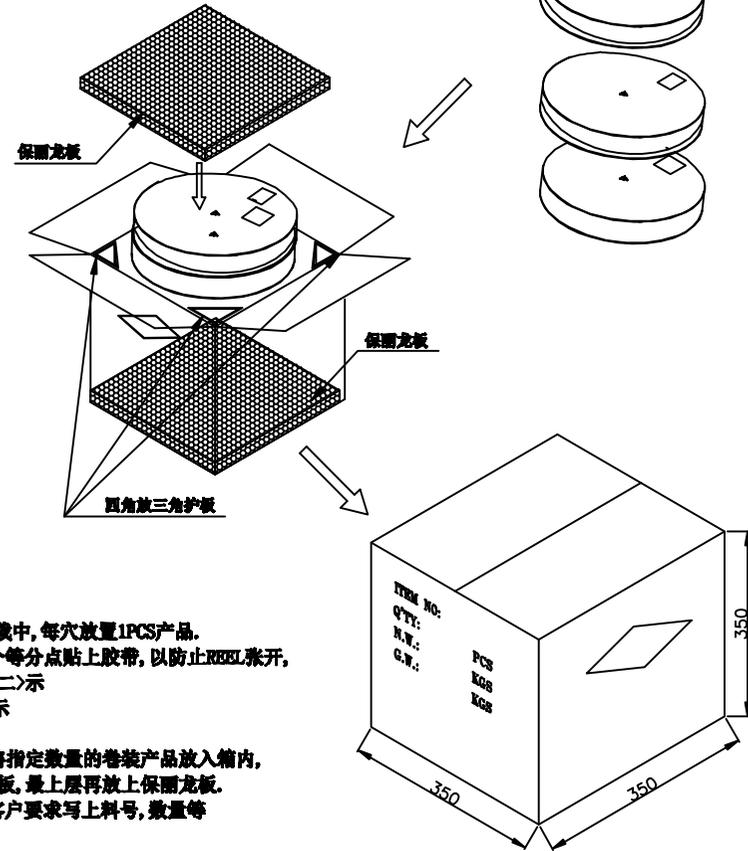
<图一>



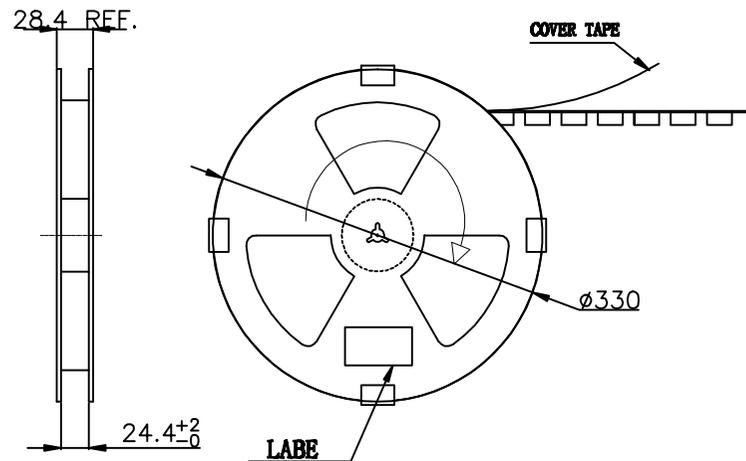
<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
1000	12	12000

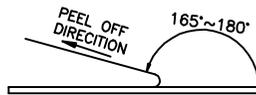
<图三>



<图二>



COVER TAPE PEELING FORCE: 20gf~120gf



NOTE:

1. 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
2. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
3. 包装数量见如<TABLE 1>示
4. 包装成箱见如<图三>示  
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
5. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

**LXW** 连兴旺电子(深圳)有限公司  
LWCONN ELECTRONICS (SHENZHEN) CO., LTD

C	PRODUCT SPEC. T#		
TITLE:	1.95H MICRO SD PUSH CONN内焊 背开型 包装图		
PART NO.	CS-376-08195W		
FILE NAME:			
SCALE	1:1	UNIT:mm	A4  SHEET: 1 of 1

工程变更通知单号 ECN(DCN) NO.	版次 REV	日期 DATE	说明 DESCRIPTION	改变 CHANGE	承认 APPRO.	General X±0.50 .X±0.30 .XX±0.20	Angle .X'±3' .XX'±2'	设计 DESIGN	校阅 CHECK	承认 APPRO.
	A	12'/08/20	NEW RELEASE					Nicolas	Nicolas	12'/08/20